102-2 Preliminary Syllabus, Da-Yeh Univ

Information			
Title	材料分析技術與實作	Serial No. / ID	0897 / EEI3120
Dept.	電機工程學系	School System / Class	大學日間部3年1班
Lecturer	李得勝	Full or Part-time	專任
Required / Credit	Optinal / 3	Graduate Class	No
Time / Place	(四)567 / H339	Language	Chinese

Introduction

- A. Department of Electrical Engineering Da-Yeh University, the aims of education (Educational Objectives)
- 1. Basic: teaching basic knowledge of mathematics and information.
- 2. Professional: professional and technical training in electrical engineering.
- 3. Integration: Strengthening the integration of technology application and training.
- 4. International outlook: foreign language skills, culture and international perspective.
- B. Department of Electrical Engineering Da-Yeh University, Education core competencies (Educational Outcomes)
- 1.1 has a basic knowledge of mathematics and ability.
- 1.2 has a physical basis of knowledge and skills.
- 1.3 has a basic knowledge of information technology and capability.
- 2.1 with electrical engineering expertise and application capability.
- 3.1 with data collection, simulation analysis, experimental design and problem solving ability.
- 3.2 necessary for engineering practice and implement the technical ability.
- 4.1 English with basic motor skills.
- 4.2 understanding of domestic motor development trend of related industries and pulse.
- 4.3 fully recognizes the importance of professional ethics, understanding of engineering technology on the environment, social and global implications, fulfilling the social responsibility of engineers.

Course Objectives:

Understanding of materials technology background, materials and applications and material analysis technology, and the basic ability to do a hands-on (A2, B2.1.B3.1, B3.2)

Outline

- 1. Materials Analysis Technology Overview
- 2. material analysis technology scanning probe microscopy
- 3. metallographic optical microscope analysis
- 4. Material analysis electron microscopy
- 5. Materials-X-ray diffraction analysis
- 6. Atomic Spectroscopy
- 7. packet materials to do real analysis sample preparation and optical diffraction
- 8. packet materials to do real analysis sample preparation and X-ray diffraction
- 9. packet materials to do real analysis sample preparation and electron microscopy
- 10. packet materials to do real analysis sample preparation and scanning probe microscopy

- 11. packet thickness analysis sample preparation and instrument operation
- 12. Grouping atoms AAS, ICP spectroscopy

Prerequisite

General Physics and Physics Experiments